ESS503 GID-5-EV03.3.4

ESS503 Ceramic Piezo-Resistive Pressure & Temperature Sensor Cell MONOLITHIC THCIK-FILM | Al203 96%



■ Range: 0~2bar~100bar/600bar ■ Size:18mm*6.35mm; 18mm*3.5mm ■ Diaphragm Material: Ceramic Al2O3 96% ■ Power Supply: 2-30V ■ Long Term Stability: 0.3%/FS ■ NTC Thermistor ■ Working Temperature: -40...+135 °C

Description

ESS503 Monolithic Pressure & Temperature Sensor Cell are made with a Ceramic Base Plate and Diaphragm and work following the piezoresistive principle. With temperature sensor mounted, ESS503 can detect temperature change via NTC Thermistor.

By integrating an **NTC thermistor**, ESS503 can continuously monitor the temperature and apply real-time compensation to the pressure readings, and can provide the necessary temperature data, allowing a more comprehensive understanding of the environment.

The Wheatstone bridge is **Screen Printed** on one side of the flush ceramic diaphragm which is, in turn, glued to the sensor's body. The bridge faces the inside where a cavity is made and the diaphragm's opposite side can therefore be exposed directly to the medium to be measured.

As the same as ESS501 and ESS502, ESS503 is also available with two kinds size: **18*6.35mm and 18*3.5mm** (thin type).

Key Features & Benefits

- Pressure range 0-2bar-100bar/600bar
- Excellent resistance to corrosion and abrasion
- Integrated with NTC Thermistor
- Thermally compensated
- Extended customization
- Extended choice of measuring ranges

Application

- Cooling equipment & A/C system
- Automotive and vehicle
- Industrial process control
- HVAC system
- Refrigeration equipment
- Air conditioning unit

Technical Characteristics

| Parameter | Unit | Description | | | |
|--------------------|------|---------------------------------------------------------------------------------------|--|--|--|
| Sensor type | - | absolute (A), gauge (R) or sealed gauge (S) | | | |
| Technology | - | Piezoresistive (Ceramic Thick Film) | | | |
| Diaphragm material | - | Ceramic Al ₂ O ₃ 96% (standard), 99.6% or sapphire (on request) | | | |
| Weight | g | ≤ 8 (ceramic cell only) | | | |
| Response time | ms | ≤1 | | | |



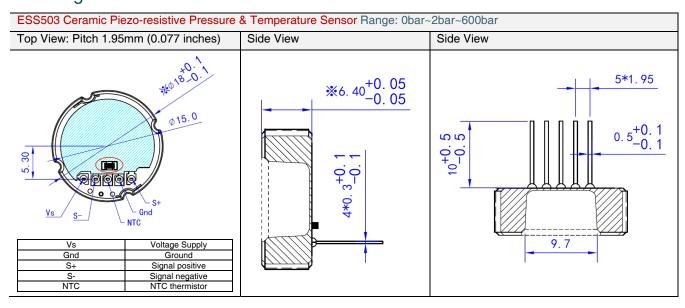


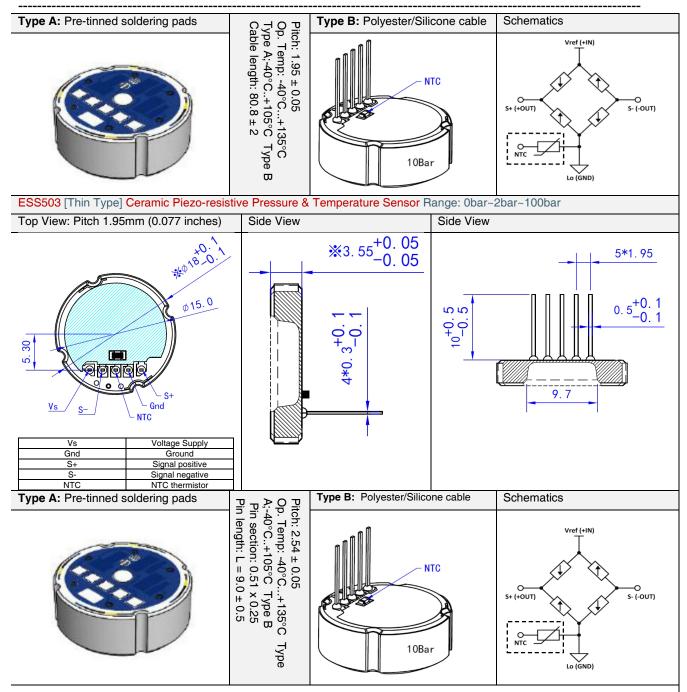
| Supply voltage | | VDC | OC 230 | | | | | | | | | | | |
|---------------------------------|--------|-------------------------|----------------------------------------------------------|-----------------------------|---------|---------|-------------------------------------------------------------------------------------------|---------|---------|---------|-------------------------------------------------------------------------------|---------|---------|--|
| Offset | | mv/v | 2 ±4 (Other nominal values available on request) | | | | | | | | | | | |
| Current mA | | | ≤ 1.3 @ 10V | | | | | | | | | | | |
| TCR | | | ≤100ppm/℃@-40℃~120℃ | | | | | | | | | | | |
| NTC | | | 10kΩ±1.5%@25°C, B=3950K | | | | | | | | | | | |
| Operating temp | °C | -40+135 (-40 °F+275 °F) | | | | | | | | | | | | |
| Storage temperature | | °C | -40+150 (-40 °F+302 °F) | | | | | | | | | | | |
| Impedance | | kΩ | 11 ± 30% | | | | | | | | | | | |
| Nominal | bar | 0.5* | 1* | 2 | 5 | 10 | 20 | 50 | 100 | 200 | 400 | 600 | 800 * | |
| pressure FSO | psi | 7 | 14 | 29 | 73 | 145 | 290 | 725 | 1450 | 2900 | 5800 | 8700 | 11600 | |
| Overload pressure | bar | 1 | 2 | 4 | 10 | 15 | 35 | 100 | 150 | 350 | 500 | 750 | 1000 | |
| | psi | 14 | 29 | 58 | 145 | 217 | 507 | 1450 | 2175 | 5075 | 7250 | 10875 | 14500 | |
| Burst pressure | bar | 2 | 3 | 6 | 15 | 25 | 65 | 120 | 200 | 500 | 650 | 950 | 1250 | |
| | psi | 29 | 43 | 87 | 217 | 362 | 942 | 1740 | 2900 | 7250 | 9425 | 13775 | 18125 | |
| Vacuum capability | bar | -0.1 | -0.5 | -0.5 | -1 | -1 | -1 | -1 | -1 | -1 | -1 | -1 | -1 | |
| | psi | -1.4 | -7 | -7 | -14 | -14 | -14 | -14 | -14 | -14 | -14 | -14 | -14 | |
| Туре | - | R | A/R/S | A/R/S | A/R/S | A/R/S | A/R/S | A/R/S | S | S | S | S | S | |
| Total thickness | mm/in | 6.40±0.05/2.51±0.2 | | | | | | | | | | | | |
| | mm/in | | $3.55 \pm 0.05 / 1.40 \pm 0.2$; for thin type | | | | | | | | | | | |
| Sensitivity | mv/v | 1.4- | 2.0-3.6 | 2.3-3.5 | 2.3-4.0 | 3.1-5.5 | 2.4-4.0 | 4.0-6.0 | 3.0-4.8 | 2.5-3.9 | 3.1-4.8 | 3.1-4.8 | 2.0-3.5 | |
| Accuracy | %/fs | 0.4/0 | 0.3/0.9 | 0.3/0.6 | 0.2/0.4 | 0.2/0.5 | 0.2/0.5 | 0.2/0.5 | 0.2/0.5 | 0.4/0.9 | 0.5/1.0 | 0.5/1.0 | 0.5/1.0 | |
| Thermal offset shift(typ./max.) | %/fs/k | ± 0.0 | ± 0.005 / ± 0.040 25 °C85 °C (77 °F185 °F) | | | | | | | | | | | |
| Thermal span shift | %/fs/k | ≤ ± 0 | $\leq \pm 0.010$ $\leq \pm 0.012$ $\leq \pm 0.014$ | | | | 0 °C70 °C -25 °C0 °C / 70 °C85 °C -40 °C25 °C / 85 °C135 °C | | | | (32 °F158 °F) (-13 °F32 °F / 158 °F185 °F) (-40 °F13 °F / 185 °F275 °F) | | | |
| Reliability tests | - | 1 | _ | 5 °C (185 °F n-in @150 ' | • | 1 | 500 thermal shocks -40°C+150 °C (-40 °F +302 °F) 10 million 0 bar to Pnom pressure cycles | | | | | | | |

Tests performed at 25°C in Eastsensor housings, unless otherwise specified. Different housings may affect performances.

- 1. Psi values for reference only. 2. The sensitivity of each production batch is constant, within the indicated range and with minimal dispersion.
- $\textbf{3.} \textit{Accuracy} = \sqrt{\textit{NonLinearity}^2 + \textit{Hysteresis}^2 + \textit{NonRepeatability}^2}, \textit{terminal based}.$
- 4. All technical characteristics will remain within indicated ranges performing the above-mentioned reliability tests. 5. Please consult manufacturer when pressure range with **"

Drawing





- 1. Storage Conditions: Store at 10~35°C with ≤ 70% RH. Avoid places that are too hot, exposed to direct sunlight, dusty, or have corrosive gases. The metal pins can easily oxidize in the air, so it's recommended to use the product within 10 days after unpacking. Under proper storage conditions, the soldering validity is 12 months. If stored for more than 12 months, the ceramic core needs to be rechecked for solderability and can only be used if it passes inspection.
- 2. Product Installation Pressure: During crimping installation, the crimping pressure should not exceed 20KN, and the direct pressure on the core should not exceed 5KN. Excessive force may damage the core structure or cause abnormal output signals. The ceramic core should not come into direct contact with hard objects like a metal casing to avoid significant internal stress and unstable output.
- 3. Sealing Recommendations: When using sealing rings, ensure that the sealing ring is centered with the elastic diaphragm and without uneven force. The inner diameter of the sealing ring should be >11.0mm and the outer diameter <16.0mm after compression deformation.
- 4. Solder Pads: The pressure core PIN is constructed of nickel-tin copper. The welding hole for the PIN measures 0.7mm, with a pad width exceeding 0.5mm. The soldering temperature must not exceed 370 °C, with each soldering session limited to under 3 seconds and a maximum of 3 sessions.



Ordering Procedure

| ESS5 | Ceramic I | Piezoresi | stive Pre | ssure Se | ensor | | | | | | | | | |
|------|-------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------|----------------------|------------------------|-----------------------------------------------|-------------------------------------------|---------------------------------------|--|--|--|--|--|--|
| | Code | Model | | | | | | | | | | | | |
| | 01 | Pressu | ire Sens | or Cell, N | , Monolithic 18*6.35mm | | | | | | | | | |
| | 01 Thin | Pressu | ire Sens | or Cell, N | /lonolithic | 18*3.35mm | nm | | | | | | | |
| | 01-1 | Pressu | re Sens | or Modul | e, Monolitl | hic (with po | nic (with pcb) 4-20mA; Electronics on PCB | | | | | | | |
| | 01-V | Pressu | re Sens | or Modul | e, Monolitl | hic (with pcb) 0.5-4.5V; Electronics on PCB | | | | | | | | |
| | 01-IIC | Pressu | re Sens | or Modul | e, Monolitl | hic (with pcb) I2C Output; Electronics on PCB | | | | | | | | |
| | 02 (18) | Pressu | ire Sens | or Cell, F | lush diaph | hragm 18*6.35mm | | | | | | | | |
| | 02 (18)Thin | Pressu | ire Sens | or Cell, F | lush diaph | hragm 18*3.35mm | | | | | | | | |
| | 02 (12) | Pressu | ire Sens | or Cell, F | lush diaph | ragm 12*12*3mm | | | | | | | | |
| | 02 (14) | Pressure Sensor Cell, Flush diaphragm 14*14*3mm Pressure Sensor Cell, Flush diaphragm 21*4.35mm | | | | | | | | | | | | |
| | 02 (21) | | | | | | | | | | | | | |
| | 02-I | Pressu | 20mA; Electronics on PCB | | | | | | | | | | | |
| | 02-IOC | Pressu | Pressure Sensor Module, Flush diaphragm (with pcb) 4-20mA; Electronics on Ceramic | | | | | | | | | | | |
| | 02-V | Pressure Sensor Module, Flush diaphragm (with pcb) 0.5-4.5V; Electronics on PCB | | | | | | | | | | | | |
| | 02-VOC | Pressure Sensor Module, Flush diaphragm (with pcb) 0.5-4.5V; Electronics on Ceramic Pressure Sensor Module, Flush diaphragm (with pcb) I2C Output; Electronics on PCB | | | | | | | | | | | | |
| | 02-IIC | | | | | | | | | | | | | |
| | 02-IICOC | Pressu | Pressure Sensor Module, Flush diaphragm (with pcb) I2C Output; Electronics on Ceramic | | | | | | | | | | | |
| | 03 | Pressu | Pressure Sensor Cell (with temperature sensor mounted), Monolithic 18*6.35mm | | | | | | | | | | | |
| | 03 Thin | Pressu | Pressure Sensor Cell (with temperature sensor mounted), Monolithic 18*3.35mm | | | | | | | | | | | |
| | | Code | Span | | | Code | Span | | | | | | | |
| | | R01 | 00.5 | bar [0 | 7psi] | R07 | 050 bar | [0720psi] | | | | | | |
| | | R02 | 01 ba | r [01 | L4psi] | R08 | 0100 bar | [01450psi] | | | | | | |
| | | R03 | 02 ba | | 29psi] | R09 | 0200 bar | [02900psi] | | | | | | |
| | | R04 | 05 ba | | 72psi] | R10 | 0400 bar | | | | | | | |
| | | R05 | 010 b | | .145psi] | R11 | 0600 bar [08700psi] | | | | | | | |
| | | R06 | 020 b | | .290psi] | R12 | 0800 bar | [011600psi] | | | | | | |
| | | | Code | Pressu | ıre Type | e Type | | | | | | | | |
| | | | R | Gauge | | | | | | | | | | |
| | | | Α | Absolu | | | | | | | | | | |
| | | | S | Sealed | d Gauge | | | | | | | | | |
| | | | | Code | | ty adjustme | ent | | | | | | | |
| | | | | 0 | Without | | | | | | | | | |
| | | | | 9 | On requ | est | | | | | | | | |
| | | | | | Code 0 | Thermal | | | | | | | | |
| | | | | ermally compensated) | | | | | | | | | | |
| | | | | | | | | | | | | | | |
| | | | | | 2 | ≤ ± 0.02 % | · | | | | | | | |
| | | | | | | Code | Termination type | | | | | | | |
| | | | | | | 02 | 5 pins, Pre-tinned pads, pitch 1.95 mm | | | | | | | |
| | | | | | | | | one single wires 80 mm, pitch 1.95 mm | | | | | | |
| | | | | | | | Code | Additional coating | | | | | | |
| | | | | | | | 1 | Without | | | | | | |
| | | | | | | | 2 | Parylene coating | | | | | | |
| ESS5 | 03 | R10 | R | 0 | 2 | 03 | 1 | | | | | | | |

Note: ① Extremely attention must be paid to sensor installation process to avoid any miss conduction that affect the sensor performance, ② please protect the diaphragm and the compensated board carefully to prevent any damage. ③ Please contact us if your requested working temperature lower than $-20 \, \text{C}$;